



Amendments to the specification:

At page 8 line 15, please insert the following paragraphs:

--Brief Description of the Drawings

FIG. 1 shows the decomposition of the di{[bis(trimethylsilyl)acetylene]-copper(I)}oxalate prepared as a function of temperature with deposition of a thin copper layer on a substrate.

FIG. 2 shows the decomposition of the di{[(trimethylsilyl)(n-butyl)acetylene]copper(I)}oxalate prepared as a function of temperature with deposition of a thin copper layer on a substrate.

FIG. 3 shows the decomposition of the di[(vinyl-t-butyl)dimethylsilane]-copper(I)]oxalate prepared as a function of temperature with deposition of a thin copper layer on a substrate.

FIG. 4 shows the decomposition of the di[(vinyl)diethylmethylsilane]-copper(I)]oxalate prepared as a function of temperature with deposition of a thin copper layer on a substrate. --